

**Amendments to the Specification:**

Please amend the paragraph beginning on page 3, line 17 as follows:

One embodiment of a reactor assembly is disclosed in U.S.S.N. 08/988,333 (now issued as U.S. Patent No. 5,985,126) filed September 30, 1997 entitled "Semiconductor Plating System Workpiece Support Having Workpiece – Engaging Electrodes With Distal Contact Part and Dielectric Cover," herein incorporated by reference. FIGURE 1 illustrates such an assembly. As illustrated, the assembly 10 includes reactor vessel 11 for electroplating a metal, and processing head 12.

Please amend the paragraph beginning on page 5, line 18 as follows:

The processing head 12 can be manipulated by a head operator as described in the aforementioned U.S. Serial No. 08/988,333 (now issued as U.S. Patent No. 5,985,126). Pivotal action of the processing head using the operator allows the processing head to be placed in an open or faced-up position (not shown) for loading and unloading wafer W.

Please amend the paragraph beginning on page 6, line 3 as follows:

Processing exhaust gas must be removed from the volume 13 as described in the aforementioned U.S. Serial No. 08/988,333 (now issued as U.S. Patent No. 5,985,126).

Please amend the paragraph beginning on page 11, line 7 as follows:

FIGURES 2-4 illustrate a reactor vessel 100 which is to be used in cooperation with a processing head 12 (as shown in FIGURE 1). The reactor vessel 100 is described in U.S. Serial No. 09/112,300 (now issued as U.S. Patent No. 6,228,232), filed July 9, 1998, titled "Reactor Vessel Having Improved Cup, Anode and Conductor Assembly", and herein incorporated by reference. The processing head 12 may, for example, be of the type disclosed in U.S. Serial No. 08/988,333 (now issued as U.S. Patent No. 5,985,126), filed September 30, 1997 entitled: "Semiconductor Plating System Workpiece Support Having Workpiece – Engaging Electrodes With Distal Contact Part and Dielectric Cover" herein incorporated by reference. The processing

head holds a wafer to be processed within a substantially closed processing volume 103 of the reactor vessel 100, and rotates the wafer during processing. The vessel 100 is shown without a vessel exhaust ring assembly for clarity to illustrate the underlying parts. It is to be understood that the outer vessel exhaust ring assembly 80 and exhaust nozzle 83 as shown for example in FIGURE 1 would be mounted around the vessel 100.

Please amend the paragraph beginning on page 14, line 8 as follows:

The diffusion plate 12 can be engaged and removed by a tool described in the aforementioned U.S. Serial No. 09/112,300 (now issued as U.S. Patent No. 6,228,232), filed July 9, 1998, and herein incorporated by reference. The tool hook arms are configured and arranged to engage bayonet recesses 330 formed through an outside of a top perforated plate 112a of the diffusion plate 112 as illustrated in FIGURES 5. Each recess 330 includes a wide region 332 for receiving a hook portion, and two narrow regions 334 for snugly receiving a leg of the tool hook arm into a locked position (in either direction depending on whether removal or installation is taking place). When the leg moves in this position, the hook portion is located below the top perforated plate 112a. The tool can be turned to rotate the diffusion plate for its removal or installation.

Please amend the paragraph beginning on page 17, line 4 as follows:

As shown in FIGURES 9 and 11A, the top shield 906 includes edge recesses 912 identical to those shown in FIGURE 5, and described above, as bayonet recesses 330. Below the shield 906, the mounting ring has a step 915 which provides a space 917 for the insertion of the hook portions of the removal tool described above and in the aforementioned U.S. Serial No. 09/112,300 (now issued as U.S. Patent No. 6,228,232), filed July 9, 1998, and herein incorporated by reference.